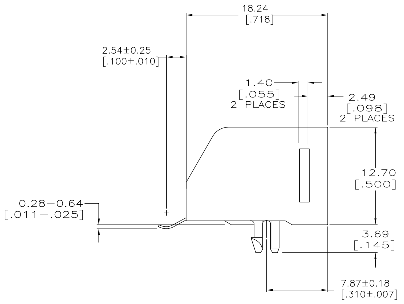
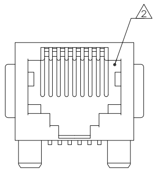
THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION −,− .

LOC AA DIST 00

REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	B	ECO−07−019669	27AUG2007	LAM	PR



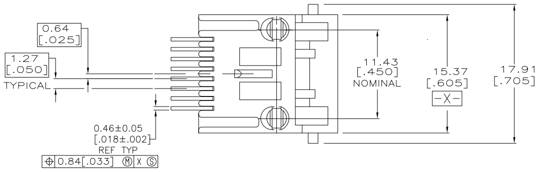


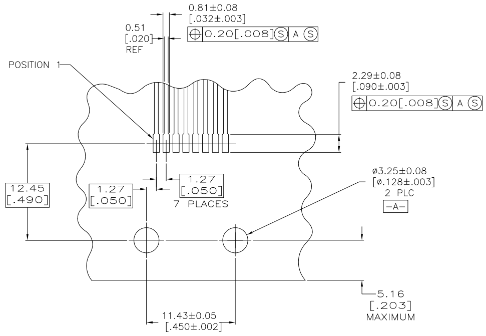
1. MATERIAL: HOUSING − HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK
   TERMINAL − 0.36 [.014] THICK PHOS−BRONZE PLATE WITH 1.27μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.

2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.

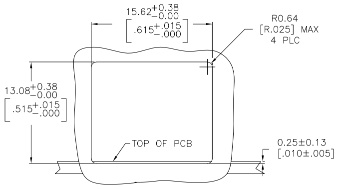
3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.

4. SNAP−IN RETENTION FEATURE ACCOMMODATES 1.45−1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.





RECOMMENDED PRINTED CIRCUIT BOARD
COMPONENT SIDE



RECOMMENDED
PANEL CUTOUT

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± −
1 PLC ± −
2 PLC ± −
3 PLC ± −
4 PLC ± −
ANGLES ± −

MATERIAL SEE NOTE 1

FINISH SEE NOTE 1

DWN G. ATTADIA − DOCK5 08JUN2005
CHK J. WESTMAN 08JUN2005
APVD S. FLICKINGER 08JUN2005
PRODUCT SPEC 108−1163
APPLICATION SPEC 114−6040
WEIGHT −

Tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105−3608

NAME
MODULAR JACK ASSEMBLY, 8 POSITION,
LOW PROFILE, RIGHT ANGLE,
SURFACE MOUNT, WITH PANEL STOPS

SIZE A1 CAGE CODE 00779 DRAWING NO C−5555248 RESTRICTED TO −

CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV B